

ABSTRACT**Electronic Printed Circuit Cooling Device and Embodiment therefor**

The present invention relates to the problem posed by the cooling of printed circuits comprising electronic components of diverse sizes, some of which exhibit strong thermal dissipation. It is particularly intended for electronics cards mounted in a rack.

5 The structure of the device comprises at least:

a rigid, preferably substantially plane wall in particular allowing easy insertion of the device into a rack equipped with electronics cards,

a thin, flexible wall with controlled elasticity having a shape similar to that of the rigid wall and of low thermal resistivity, the edges of which
10 adhere to the edges of the rigid walls so as to create a leaktight heat exchange space whose volume can vary,

- means comprising channels such that a coolant can be made to penetrate and diffuse in the heat exchange space. In order to facilitate fitting and removal of the device, these channels are equipped with self-closing
15 nozzles.

The device can be adapted to various types of electronics cards and racks.

Figure 1



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